

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-46 (Canceled)

Claim 47 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said tip structure is integrally formed with said ~~interconnection element~~ one of the interconnection elements.

Claim 48 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said ~~interconnection element~~ one of the interconnection elements comprises a buckling beam interconnection element.

Claim 49 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said ~~interconnection element~~ one of the interconnection elements is resilient.

Claims 50 and 51 (Canceled)

Claim 52 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said blade comprises a sharpened edge along said length thereof.

Claim 53 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said tip structure comprises at least one of palladium, cobalt, rhodium, tungsten, or diamond.

Claim 54 (Currently amended): The ~~tested device~~ semiconductor die of ~~claim 46~~ claim 67, wherein said tip structure comprises a material comprising a spring alloy.

Claim 55 (Currently amended): The ~~tested device~~ semiconductor die of claim 46 ~~claim 67~~, wherein said tip structure is secured to said ~~interconnection element~~ one of the interconnection elements by one of braze or solder.

Claims 56-59 (Canceled)

Claim 60 (New): A semiconductor die tested by making temporary electrical connections between interconnection elements of a contactor device and terminals of the die, the method of making the temporary electrical connections comprising:

forcing into contact blades of ones of the interconnection elements and ones of the terminals,

the blades deflecting across the terminals in a motion that is within plus or minus forty-five degrees of an axis corresponding to a length of the blade.

Claim 61 (New): The semiconductor die of claim 60, wherein the deflecting motion is within plus or minus thirty degrees of the axis corresponding to the length of the blade.

Claim 62 (New): The semiconductor die of claim 60, wherein the deflecting motion is approximately parallel to the axis corresponding to the length of the blade.

Claim 63 (New): The semiconductor die of claim 60, wherein the blades cut through oxide layers formed on the terminals.

Claim 64 (New): The semiconductor die of claim 60, wherein the blades cut into the terminals.

Claim 65 (New): The semiconductor die of claim 60, wherein the blades are sharpened.

Claim 66 (New): The semiconductor die of claim 60, wherein the blades comprise a truncated pyramid shape.

Claim 67 (New): The semiconductor die of claim 60, wherein each of the blades composes a tip structure disposed on one of the interconnection elements.